

# Analog Multiplexers/ Demultiplexers with Injection Current Effect Control

Automotive Customized

## MC74HC4851A, MC74HC4852A, MC74HCT4851A, MC74HCT4852A

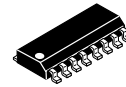
These devices are pin compatible to standard HC405x and MC1405xB analog mux/demux devices, but feature injection current effect control. This makes them especially suited for usage in automotive applications where voltages in excess of normal logic voltage are common.

The injection current effect control allows signals at disabled analog input channels to exceed the supply voltage range without affecting the signal of the enabled analog channel. This eliminates the need for external diode/resistor networks typically used to keep the analog channel signals within the supply voltage range.

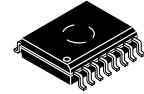
The devices utilize low power silicon gate CMOS technology. The Channel Select and Enable inputs are compatible with standard CMOS outputs.

### Features

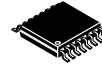
- Injection Current Cross-Coupling Less than 1 mV/mA (See Figure 10)
- Pin Compatible to HC405X and MC1405XB Devices
- Power Supply Range 2.0 to 6.0 V (HC), 4.5 to 5.5 V (HCT)
- In Compliance With the Requirements of JEDEC Standard No. 7 A
- Chip Complexity: 154 FETs or 36 Equivalent Gates
- -Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant



SOIC-16  
D SUFFIX  
CASE 751B



SOIC-16 WIDE  
DW SUFFIX  
CASE 751G

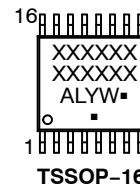
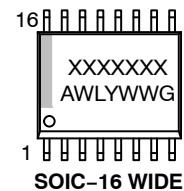
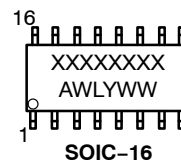


TSSOP-16  
DT SUFFIX  
CASE 948F



QFN16  
MN SUFFIX  
CASE 485AW

### MARKING DIAGRAMS



\*V4851 marking used for  
NLV74HC4851AMN1TWG

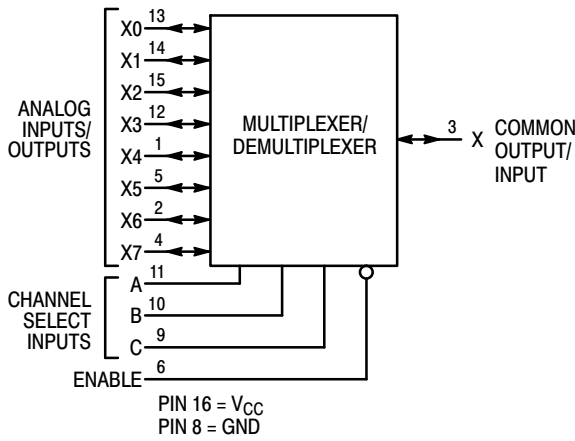
XXXXXXX = Specific Device Code  
A = Assembly Location  
WL, L = Wafer Lot  
YY, Y = Year  
WW, W = Work Week  
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

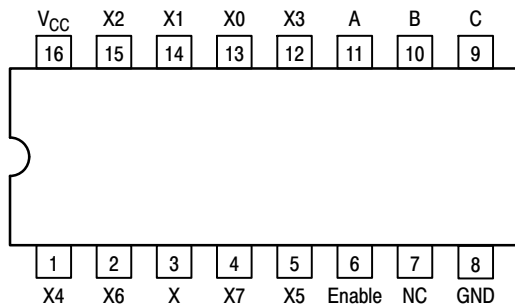
### ORDERING INFORMATION

See detailed ordering and shipping information on page 15 of this data sheet.

# MC74HC4851A, MC74HC4852A, MC74HCT4851A, MC74HCT4852A



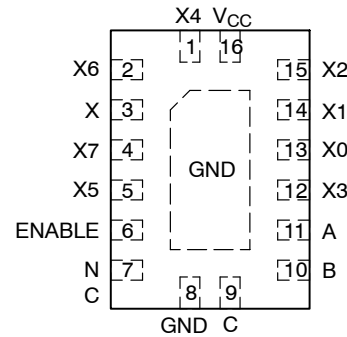
**Figure 1. 4851A Logic Diagram**  
Single-Pole, 8-Position Plus Common Off



**Figure 2. 4851A 16-Lead Pinout (Top View)**

**FUNCTION TABLE - 4851A**

Control Inputs				ON Channels
Enable	Select			
	C	B	A	
L	L	L	L	X0
L	L	L	H	X1
L	L	H	L	X2
L	L	H	H	X3
L	H	L	L	X4
L	H	L	H	X5
L	H	H	L	X6
L	H	H	H	X7
H	X	X	X	NONE

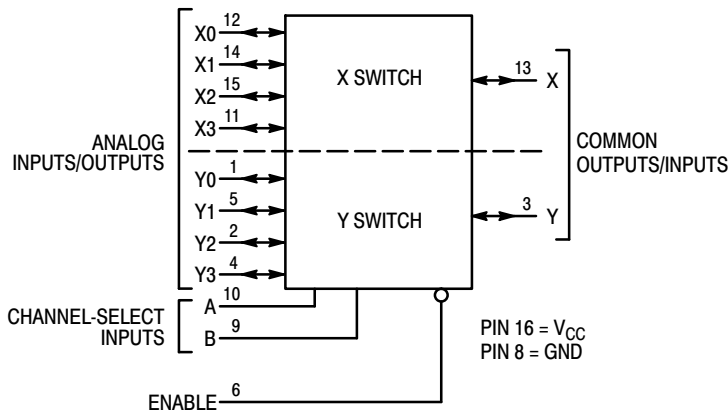


**Figure 3. 4851A QFN Pinout**

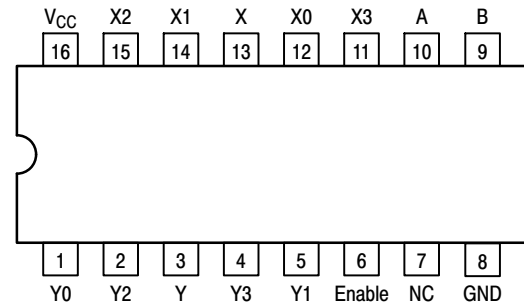
**FUNCTION TABLE - 4852A**

Control Inputs			ON Channels	
Enable	Select			
	B	A		
L	L	L	Y0	X0
L	L	H	Y1	X1
L	H	L	Y2	X2
L	H	H	Y3	X3
H	X	X	NONE	

X = Don't Care



**Figure 4. 4852A Logic Diagram**  
Double-Pole, 4-Position Plus Common Off



**Figure 5. 4852A 16-Lead Pinout (Top View)**

# MC74HC4851A, MC74HC4852A, MC74HCT4851A, MC74HCT4852A

## MAXIMUM RATINGS

Symbol	Parameter	Value	Unit	
$V_{CC}$	DC Supply Voltage	-0.5 to +6.5	V	
$V_{IN}$	DC Input Voltage	-0.5 to $V_{CC}+0.5$	V	
$I_{IN}$	DC Input Current, per Pin	$\pm 25$	mA	
$I_{CC}$	DC Supply Current, $V_{CC}$ and GND Pins	$\pm 50$	mA	
$I_{IK}$	Input Clamp Current ( $V_{IN} < 0$ or $V_{IN} > V_{CC}$ )	$\pm 20$	mA	
$I_{OK}$	Output Clamp Current ( $V_{OUT} < 0$ or $V_{OUT} > V_{CC}$ )	$\pm 20$	mA	
$T_{STG}$	Storage Temperature Range	-65 to +150	$^{\circ}\text{C}$	
$T_L$	Lead Temperature, 1 mm from Case for 10 secs	260	$^{\circ}\text{C}$	
$T_J$	Junction Temperature Under Bias	+150	$^{\circ}\text{C}$	
$\theta_{JA}$	Thermal Resistance (Note 1)	SOIC-16	126	$^{\circ}\text{C}/\text{W}$
		QFN16	118	
		TSSOP-16	159	
$P_D$	Power Dissipation in Still Air at 25 $^{\circ}\text{C}$	SOIC-16	995	mW
		QFN16	1062	
		TSSOP-16	787	
MSL	Moisture Sensitivity	Level 1	-	
$F_R$	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	-
$V_{ESD}$	ESD Withstand Voltage (Note 2)	Human Body Model	> 2000	V
		Charged Device Model	N/A	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 76 mm-by-114 mm, 2-ounce copper trace no air flow per JESD51-7.
2. HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
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### MC74HC

$V_{CC}$	DC Supply Voltage (Referenced to GND)	2.0	6.0	V	
$V_{IN}$	DC Input Voltage – Any Pin (Referenced to GND)	0	$V_{CC}$	V	
$V_{IO*}$	Static or Dynamic Voltage Across Switch	0	1.2	V	
$T_A$	Operating Free-Air Temperature	-55	+125	$^{\circ}\text{C}$	
$t_r, t_f$	Input Rise or Fall Time	$V_{CC} = 2.0\text{ V}$	0	1000	ns
		$V_{CC} = 4.5\text{ V}$	0	500	
		$V_{CC} = 6.0\text{ V}$	0	400	

### MC74HCT

$V_{CC}$	DC Supply Voltage (Referenced to GND)	4.5	5.5	V	
$V_{IN}$	DC Input Voltage – Any Pin (Referenced to GND)	0	$V_{CC}$	V	
$V_{IO*}$	Static or Dynamic Voltage Across Switch	0	1.2	V	
$T_A$	Operating Free-Air Temperature	-55	+125	$^{\circ}\text{C}$	
$t_r, t_f$	Input Rise or Fall Time	$V_{CC} = 4.5\text{ V}$	0	500	ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

3. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or VCC). Unused outputs must be left open.

# MC74HC4851A, MC74HC4852A, MC74HCT4851A, MC74HCT4852A

## DC CHARACTERISTICS – Digital Section (MC74HC4851A, MC74HC4852A)

Symbol	Parameter	Condition	V <sub>CC</sub> V	Guaranteed Limit			Unit
				-55 to 25°C	≤85°C	≤125°C	
V <sub>IH</sub>	Minimum High-Level Input Voltage, Channel-Select or Enable Inputs	R <sub>on</sub> = Per Spec	2.0	1.50	1.50	1.50	V
			3.0	2.10	2.10	2.10	
			4.5	3.15	3.15	3.15	
			6.0	4.20	4.20	4.20	
V <sub>IL</sub>	Maximum Low-Level Input Voltage, Channel-Select or Enable Inputs	R <sub>on</sub> = Per Spec	2.0	0.50	0.50	0.50	V
			3.0	0.90	0.90	0.90	
			4.5	1.35	1.35	1.35	
			6.0	1.80	1.80	1.80	
I <sub>in</sub>	Maximum Input Leakage Current on Digital Pins (Enable/A/B/C)	V <sub>in</sub> = V <sub>CC</sub> or GND	6.0	±0.1	±1.0	±1.0	μA
I <sub>CC</sub>	Maximum Quiescent Supply Current (per Package)	V <sub>in(digital)</sub> = V <sub>CC</sub> or GND V <sub>in(analog)</sub> = GND	6.0	2	20	40	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## DC CHARACTERISTICS – Analog Section (MC74HC4851A, MC74HC4852A)

Symbol	Parameter	Condition	V <sub>CC</sub>	Guaranteed Limit			Unit
				-55 to 25°C	≤85°C	≤125°C	
R <sub>on</sub>	Maximum "ON" Resistance	V <sub>in</sub> = V <sub>IL</sub> or V <sub>IH</sub> ; V <sub>IS</sub> = V <sub>CC</sub> to GND (Note 4); I <sub>S</sub> ≤ 2.0 mA (Note 5)	2.0	1700	1750	1800	Ω
			3.0	1100	1200	1300	
			4.5	550	650	750	
			6.0	400	500	600	
ΔR <sub>on</sub>	Delta "ON" Resistance	V <sub>in</sub> = V <sub>IL</sub> or V <sub>IH</sub> ; V <sub>IS</sub> = V <sub>CC</sub> /2 (Note 4); I <sub>S</sub> ≤ 2.0 mA (Note 5)	2.0	300	400	500	Ω
			3.0	160	200	240	
			4.5	80	100	120	
			6.0	60	80	100	
I <sub>off</sub>	Maximum Off-Channel Leakage Current, Any One Channel Common Channel	V <sub>in</sub> = V <sub>CC</sub> or GND	6.0	±0.1 ±0.1	±0.1 ±0.1	±0.1 ±0.1	μA
I <sub>on</sub>	Maximum On-Channel Leakage Channel-to-Channel	V <sub>in</sub> = V <sub>CC</sub> or GND	6.0	±0.1	±0.1	±0.1	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. V<sub>IS</sub> is the input voltage of an analog I/O pin.

5. I<sub>S</sub> is the current flowing in or out of analog I/O pin.

## AC CHARACTERISTICS (MC74HC4851A, MC74HC4852A) (C<sub>L</sub> = 50 pF)

Symbol	Parameter	V <sub>CC</sub>	-55 to 25°C	≤85°C	≤125°C	Unit
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay, Analog Input to Analog Output	2.0	160	180	200	ns
		3.0	80	90	100	
		4.5	40	45	50	
		6.0	30	35	40	
t <sub>PHL</sub> , t <sub>PHZ,PZH</sub> , t <sub>PLH</sub> , t <sub>PLZ,PZL</sub>	Maximum Propagation Delay, Enable or Channel-Select to Analog Output	2.0	260	280	300	ns
		3.0	160	180	200	
		4.5	80	90	100	
		6.0	78	80	80	
C <sub>in</sub>	Maximum Input Capacitance (All Switches Off) Any Single Analog Pin (All Switches Off) Common Analog Pin		10	10	10	pF
			35	35	35	
			40	40	40	
C <sub>PD</sub>	Power Dissipation Capacitance	Typical	5.0	20		pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# MC74HC4851A, MC74HC4852A, MC74HCT4851A, MC74HCT4852A

## INJECTION CURRENT COUPLING SPECIFICATIONS (MC74HC4851A, MC74HC4852A) ( $V_{CC} = 5\text{ V}$ , $T_A = -55^\circ\text{C}$ to $+125^\circ\text{C}$ )

Symbol	Parameter	Condition	Typ	Max	Unit
$V_{\Delta out}$	Maximum Shift of Output Voltage of Enabled Analog Channel	$I_{in}^* \leq 1\text{ mA}$ , $R_S \leq 3,9\text{ k}\Omega$ $I_{in}^* \leq 10\text{ mA}$ , $R_S \leq 3,9\text{ k}\Omega$ $I_{in}^* \leq 1\text{ mA}$ , $R_S \leq 20\text{ k}\Omega$ $I_{in}^* \leq 10\text{ mA}$ , $R_S \leq 20\text{ k}\Omega$	0.1 1.0 0.5 5.0	1.0 5.0 2.0 20	mV

\* $I_{in}$  = Total current injected into all disabled channels.

## DC CHARACTERISTICS – Digital Section (MC74HCT4851A, MC74HCT4852A)

Symbol	Parameter	Condition	$V_{CC}$ V	Guaranteed Limit			Unit
				$-55$ to $25^\circ\text{C}$	$\leq 85^\circ\text{C}$	$\leq 125^\circ\text{C}$	
$V_{IH}$	Minimum High-Level Input Voltage, Channel-Select or Enable Inputs	$R_{on} = \text{Per Spec}$	4.5 to 5.5	2.0	2.0	2.0	V
$V_{IL}$	Maximum Low-Level Input Voltage, Channel-Select or Enable Inputs	$R_{on} = \text{Per Spec}$	4.5 to 5.5	0.8	0.8	0.8	V
$I_{in}$	Maximum Input Leakage Current on Digital Pins (Enable/A/B/C)	$V_{in} = V_{CC}$ or GND	5.5	$\pm 0.1$	$\pm 1.0$	$\pm 1.0$	$\mu\text{A}$
$I_{CC}$	Maximum Quiescent Supply Current (per Package)	$V_{in(\text{digital})} = V_{CC}$ or GND $V_{in(\text{analog})} = \text{GND}$	5.5	2.0	20	40	$\mu\text{A}$

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## DC CHARACTERISTICS – Analog Section (MC74HCT4851A, MC74HCT4852A)

Symbol	Parameter	Condition	$V_{CC}$	Guaranteed Limit			Unit
				$-55$ to $25^\circ\text{C}$	$\leq 85^\circ\text{C}$	$\leq 125^\circ\text{C}$	
$R_{on}$	Maximum "ON" Resistance	$V_{in} = V_{IL}$ or $V_{IH}$ ; $V_{IS} = V_{CC}$ to GND (Note 4); $I_S \leq 2.0\text{ mA}$ (Note 5)	4.5 5.5	550 400	650 500	750 600	$\Omega$
$\Delta R_{on}$	Delta "ON" Resistance	$V_{in} = V_{IL}$ or $V_{IH}$ ; $V_{IS} = V_{CC}/2$ (Note 4); $I_S \leq 2.0\text{ mA}$ (Note 5)	4.5 5.5	80 60	100 80	120 100	$\Omega$
$I_{off}$	Maximum Off-Channel Leakage Current, Any One Channel Common Channel	$V_{in} = V_{CC}$ or GND	5.5	$\pm 0.1$ $\pm 0.1$	$\pm 0.1$ $\pm 0.1$	$\pm 0.1$ $\pm 0.1$	$\mu\text{A}$
$I_{on}$	Maximum On-Channel Leakage Channel-to-Channel	$V_{in} = V_{CC}$ or GND	5.5	$\pm 0.1$	$\pm 0.1$	$\pm 0.1$	$\mu\text{A}$

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# MC74HC4851A, MC74HC4852A, MC74HCT4851A, MC74HCT4852A

## AC CHARACTERISTICS (MC74HCT4851A, MC74HCT4852A) ( $C_L = 50$ pF)

Symbol	Parameter	$V_{CC}$	-55 to 25°C	≤85°C	≤125°C	Unit
$t_{PHL}$ , $t_{PLH}$	Maximum Propagation Delay, Analog Input to Analog Output	5.0	40	45	50	ns
$t_{PHL}$ , $t_{PHZ,PZH}$ , $t_{PLH}$ , $t_{PLZ,PZL}$	Maximum Propagation Delay, Enable or Channel-Select to Analog Output	5.0	80	90	100	ns
$C_{in}$	Maximum Input Capacitance (All Switches Off)					pF
	Digital Pins		10	10	10	
	Any Single Analog Pin		35	35	35	
	Common Analog Pin		40	40	40	
$C_{PD}$	Power Dissipation Capacitance Typical	5.0	20			pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## INJECTION CURRENT COUPLING SPECIFICATIONS (MC74HCT4851A, MC74HCT4852A) ( $V_{CC} = 5$ V, $T_A = -55^\circ\text{C}$ to $+125^\circ\text{C}$ )

Symbol	Parameter	Condition	Typ	Max	Unit
$V_{\Delta_{out}}$	Maximum Shift of Output Voltage of Enabled Analog Channel	$I_{in}^* \leq 1$ mA, $R_S \leq 3,9$ k $\Omega$	0.1	1.0	mV
		$I_{in}^* \leq 10$ mA, $R_S \leq 3,9$ k $\Omega$	1.0	5.0	
		$I_{in}^* \leq 1$ mA, $R_S \leq 20$ k $\Omega$	0.5	2.0	
		$I_{in}^* \leq 10$ mA, $R_S \leq 20$ k $\Omega$	5.0	20	

\* $I_{in}$  = Total current injected into all disabled channels.

MC74HC4851A, MC74HC4852A, MC74HCT4851A, MC74HCT4852A

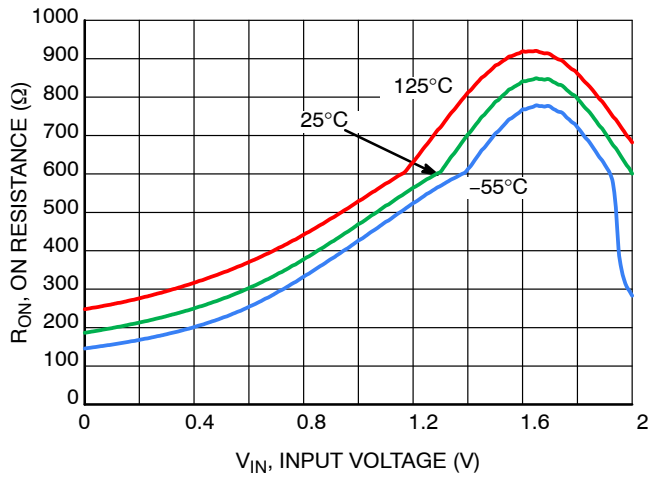


Figure 6. Typical On Resistance  $V_{CC} = 2\text{ V}$

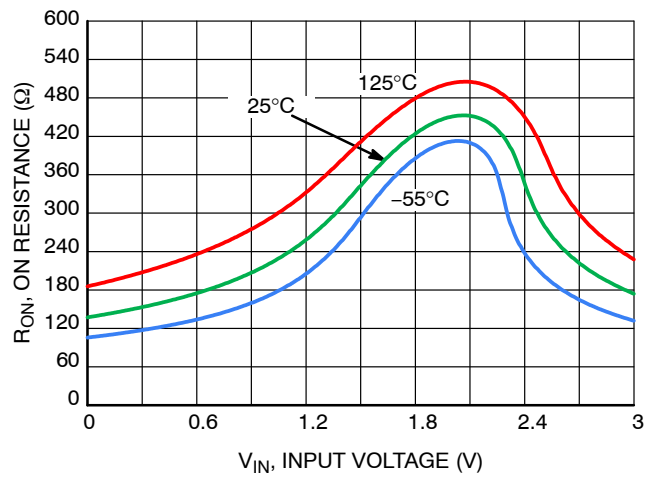


Figure 7. Typical On Resistance  $V_{CC} = 3\text{ V}$

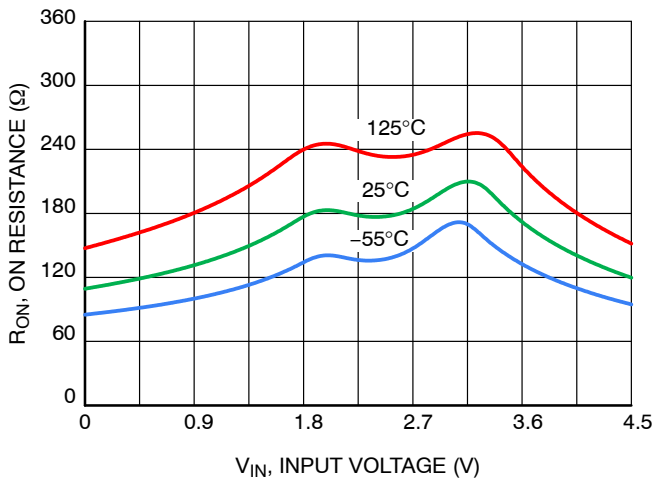


Figure 8. Typical On Resistance  $V_{CC} = 4.5\text{ V}$

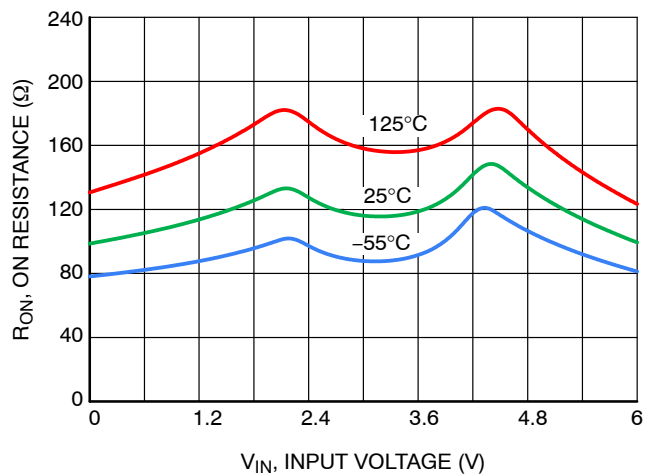


Figure 9. Typical On Resistance  $V_{CC} = 6\text{ V}$

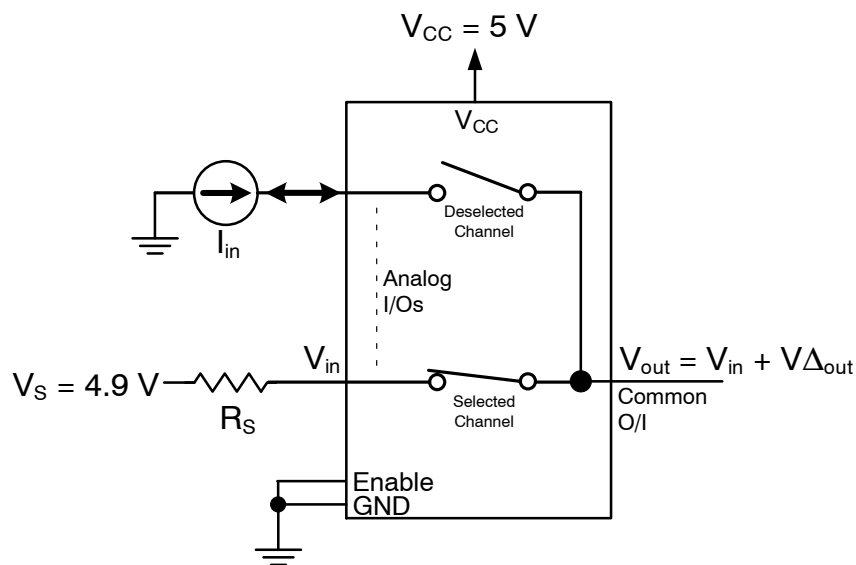


Figure 10. Injection Current Coupling Specification





TEST SETUPS

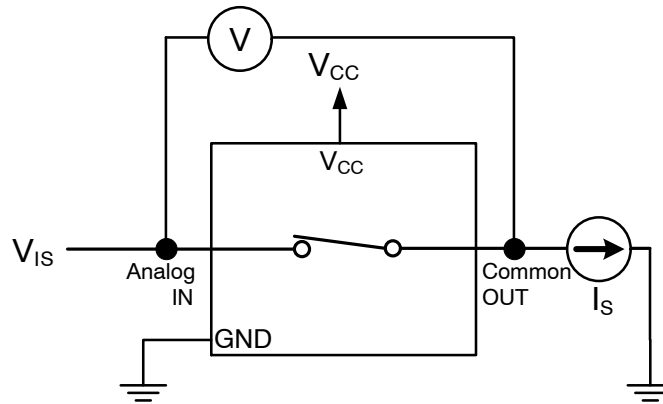


Figure 13. On Resistance

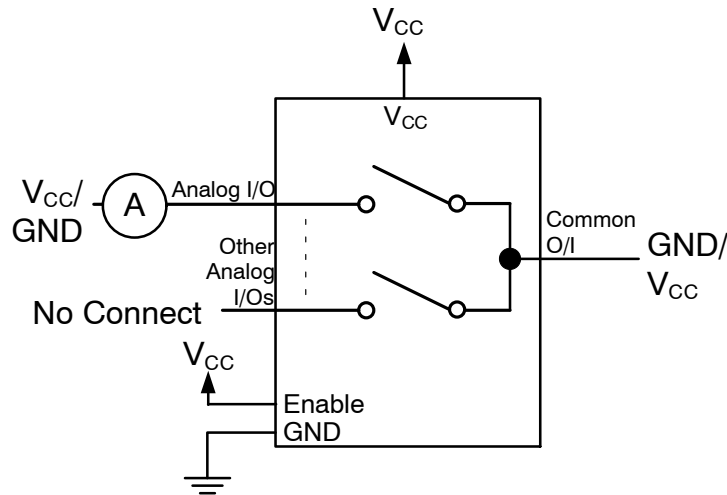


Figure 14. Maximum Off Channel Leakage Current, Any One Channel

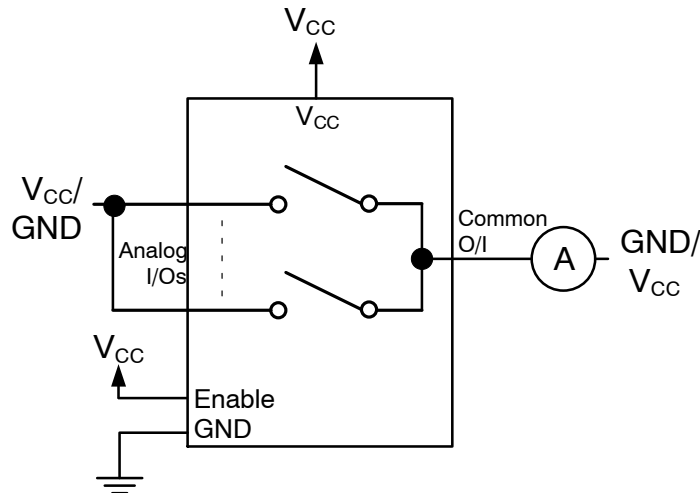


Figure 15. Maximum Off Channel Leakage Current, Common Channel

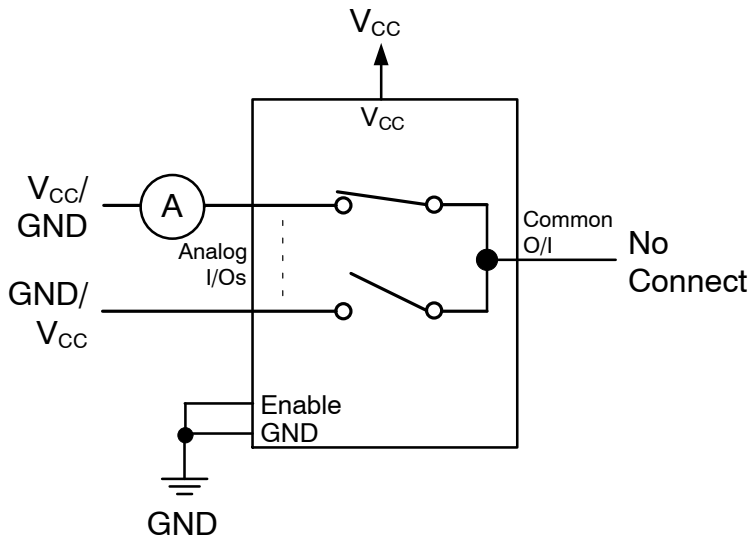
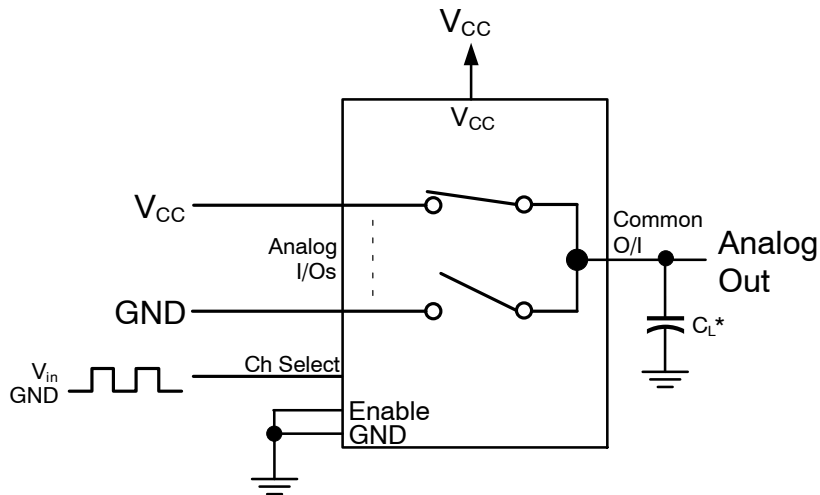
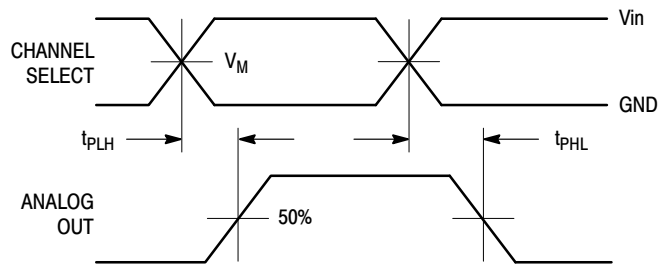


Figure 16. Maximum On Channel Leakage Current, Channel to Channel



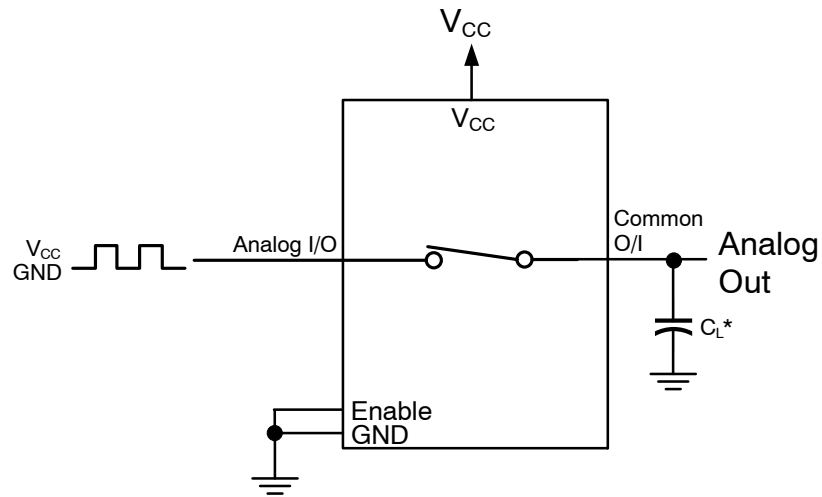
\*Includes all probe and jig capacitance.



$V_{in} = V_{CC}$  for HC, 3 V for HCT  
 $V_M = 50\% \times V_{CC}$  for HC, 1.3 V for HCT

Figure 17. Propagation Delay, Channel Select to Analog Out

# MC74HC4851A, MC74HC4852A, MC74HCT4851A, MC74HCT4852A



\*Includes all probe and jig capacitance.

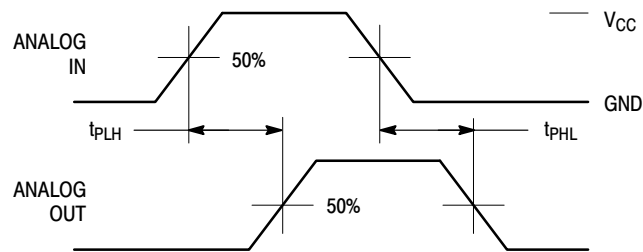
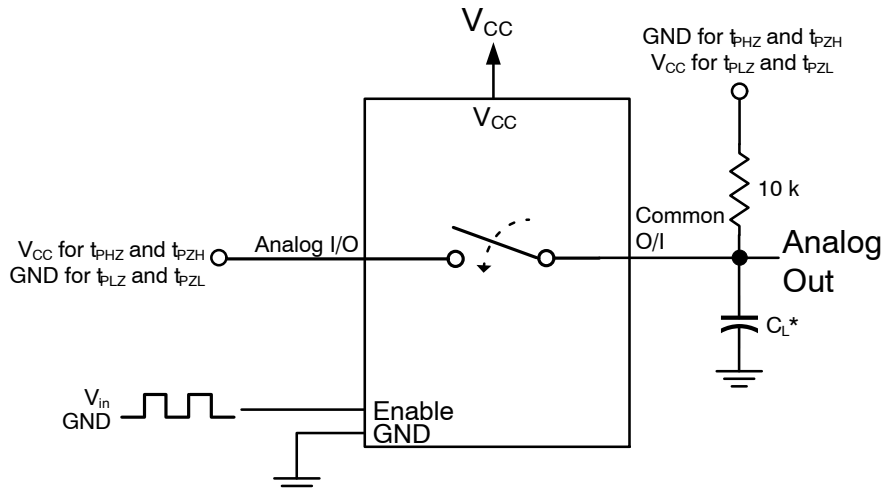


Figure 18. Propagation Delay, Analog In to Analog Out



\*Includes all probe and jig capacitance.

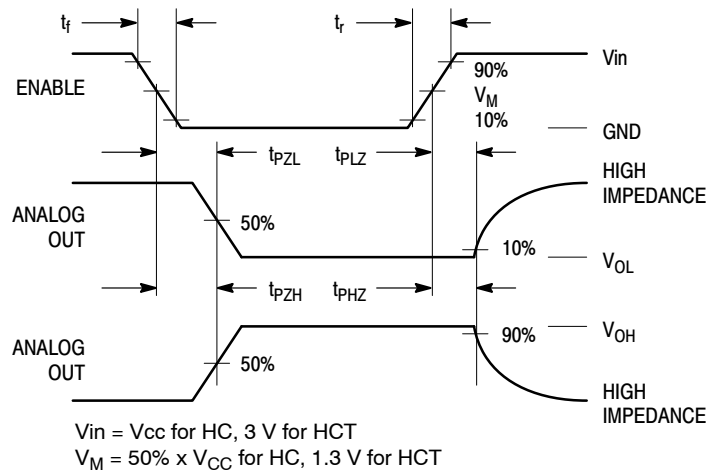


Figure 19. Propagation Delay, Enable to Analog Out

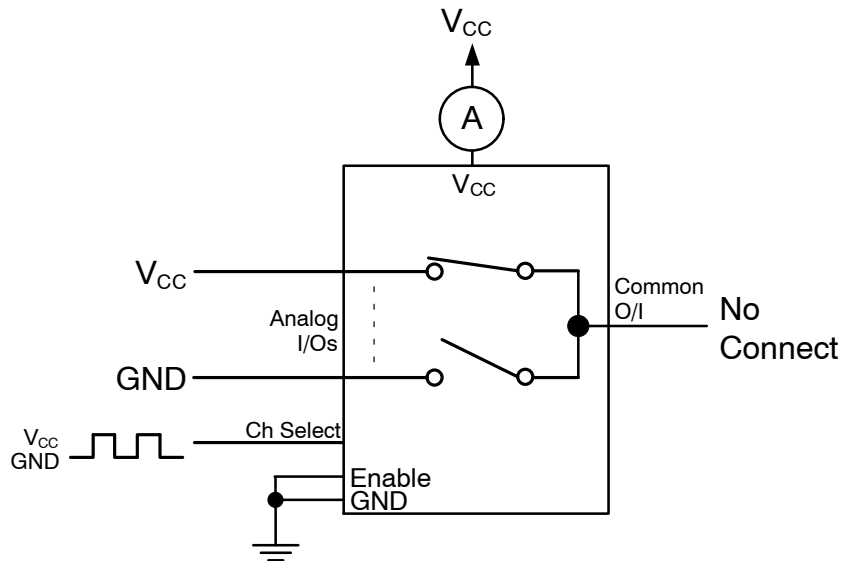
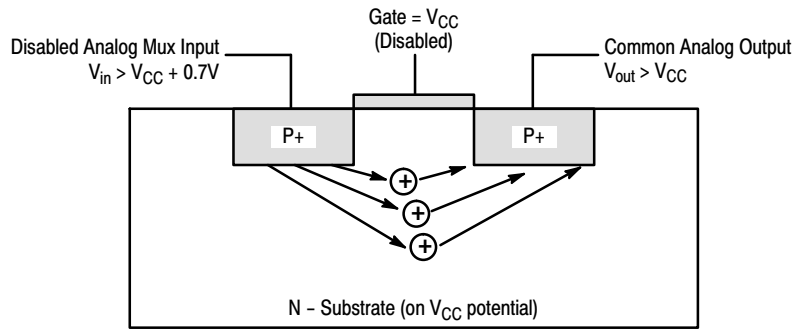
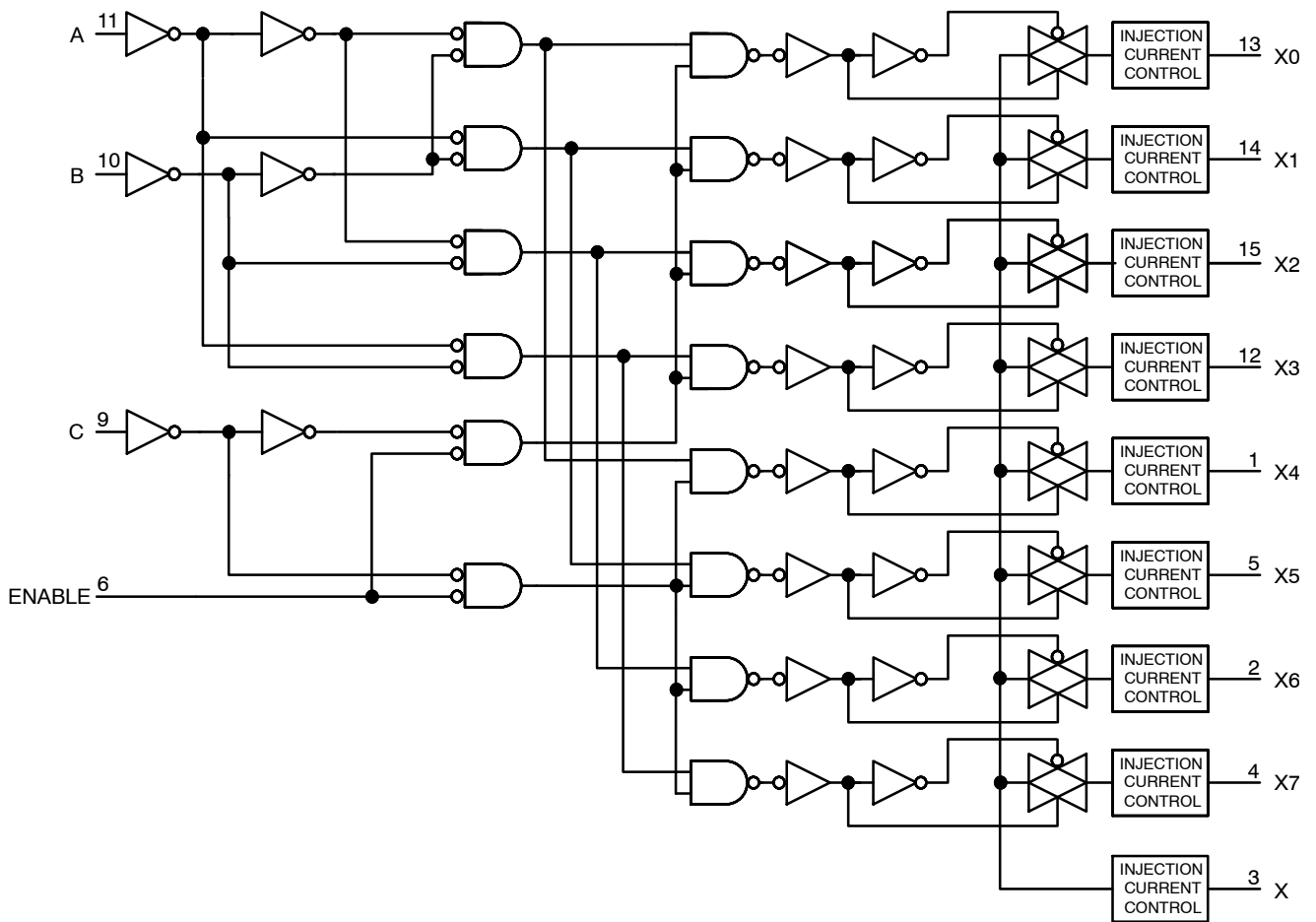


Figure 20. Power Dissipation Capacitance

**MC74HC4851A, MC74HC4852A, MC74HCT4851A, MC74HCT4852A**



**Figure 21. Diagram of Bipolar Coupling Mechanism**  
 Appears if  $V_{in}$  exceeds  $V_{CC}$ , driving injection current into the substrate



**Figure 22. Function Diagram, 4851A**

MC74HC4851A, MC74HC4852A, MC74HCT4851A, MC74HCT4852A

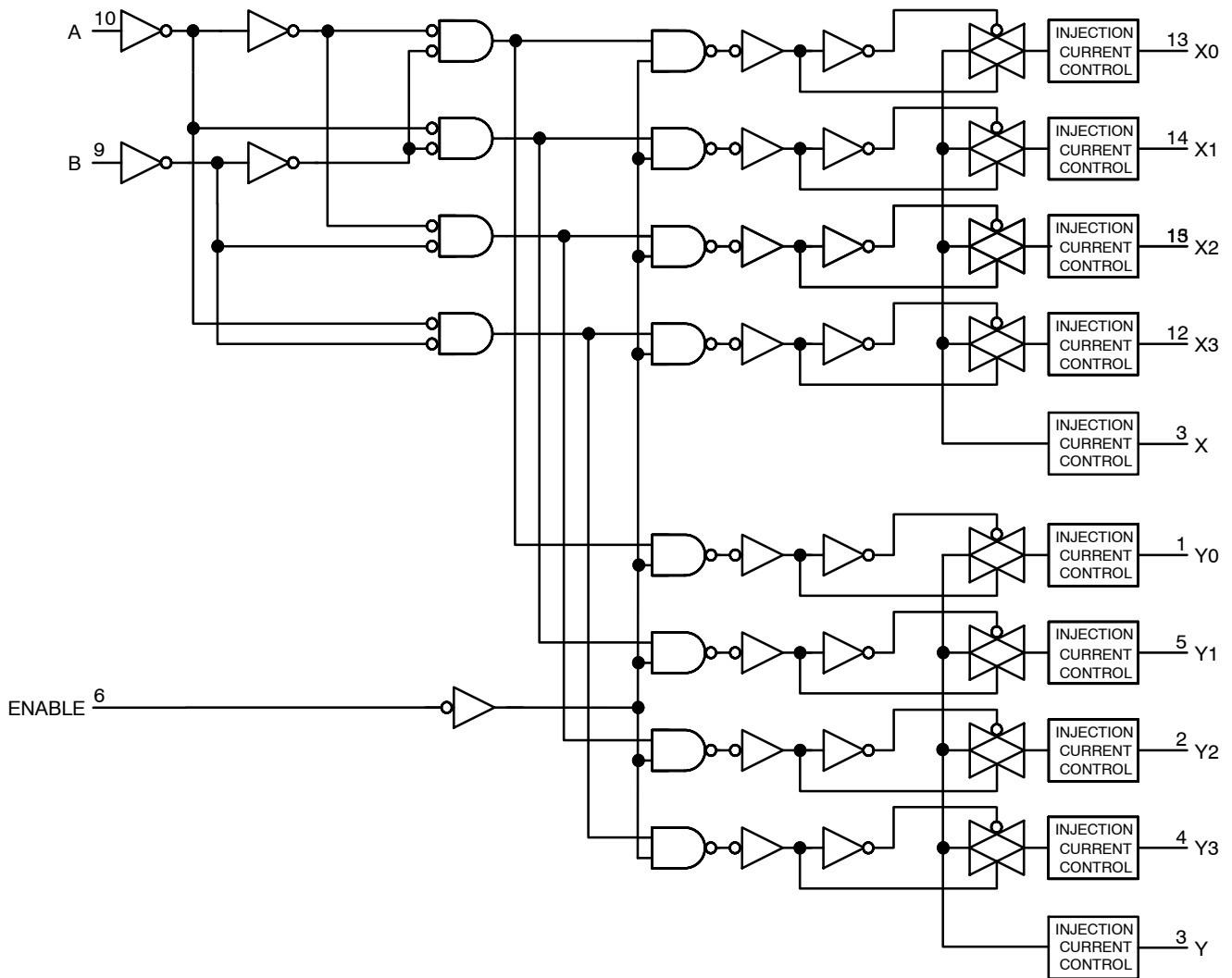


Figure 23. Function Diagram, 4852A

# MC74HC4851A, MC74HC4852A, MC74HCT4851A, MC74HCT4852A

## ORDERING INFORMATION

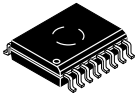
Device	Marking	Package	Shipping <sup>†</sup>
MC74HC4851ADG	HC4851AG	SOIC-16	55 Units / Rail
MC74HC4851ADR2G	HC4851AG	SOIC-16	2500 / Tape & Reel
MC74HC4851ADR2G-Q*	HC4851AG	SOIC-16	2500 / Tape & Reel
MC74HC4851ADTR2G	HC48 51A	TSSOP-16	2500 / Tape & Reel
MC74HC4851ADTR2G-Q*	HC48 51A	TSSOP-16	2500 / Tape & Reel
MC74HC4851AMN1TWG-Q*	4851	QFN-16	3000 / Tape & Reel
MC74HC4852ADR2G	HC4852AG	SOIC-16	2500 / Tape & Reel
MC74HC4852ADR2G-Q*	HC4852AG	SOIC-16	2500 / Tape & Reel
MC74HC4852ADTR2G	HC48 52A	TSSOP-16	2500 / Tape & Reel
MC74HC4852ADTR2G-Q*	HC48 52A	TSSOP-16	2500 / Tape & Reel
MC74HCT4851ADR2G	HCT4851AG	SOIC-16	2500 / Tape & Reel
MC74HCT4851ADTR2G	HCT4 851A	TSSOP-16	2500 / Tape & Reel
MC74HCT4851ADTR2G-Q*	HCT4 851A	TSSOP-16	2500 / Tape & Reel
MC74HCT4852ADR2G	HCT4852AG	SOIC-16	2500 / Tape & Reel
MC74HCT4852ADTR2G	HCT4 852A	TSSOP-16	2500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*-Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

# MC74HC4851A, MC74HC4852A, MC74HCT4851A, MC74HCT4852A

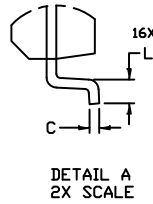
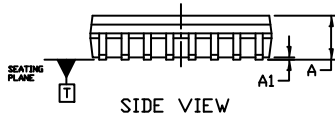
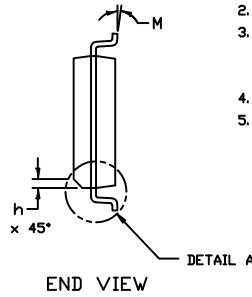
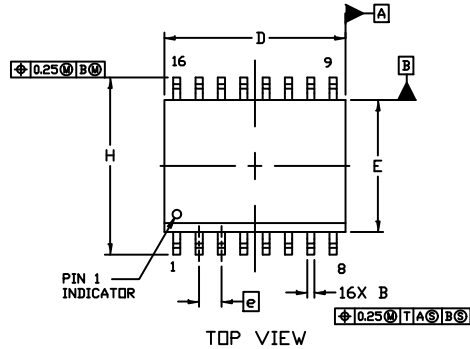
## PACKAGE DIMENSIONS



1  
SCALE 1:1

SOIC-16 WB  
CASE 751G  
ISSUE E

DATE 08 OCT 2021

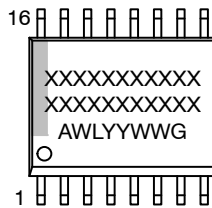


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION OR FLASH TO BE 0.15 PER SIDE.

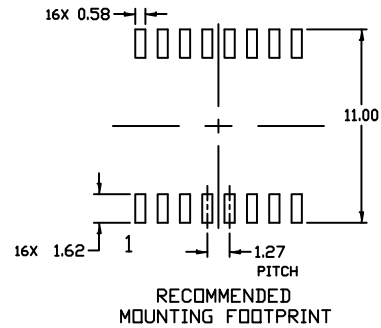
DIM	MILLIMETERS	
	MIN.	MAX.
A	2.35	2.65
A1	0.10	0.25
B	0.35	0.49
C	0.23	0.32
D	10.15	10.45
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.53 REF	
L	0.50	0.90
M	0°	7°

### GENERIC MARKING DIAGRAM\*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.





# MC74HC4851A, MC74HC4852A, MC74HCT4851A, MC74HCT4852A

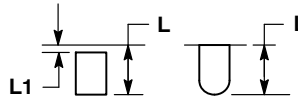
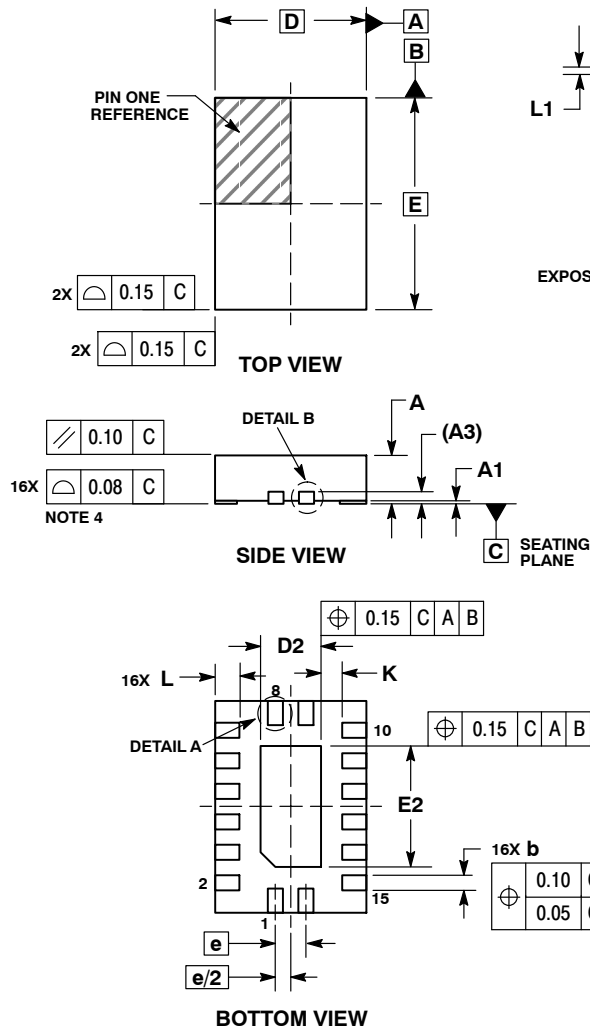
## PACKAGE DIMENSIONS



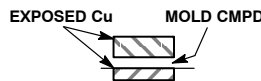
SCALE 2:1

QFN16, 2.5x3.5, 0.5P  
CASE 485AW  
ISSUE O

DATE 11 DEC 2008



**DETAIL A**  
ALTERNATE TERMINAL  
CONSTRUCTIONS



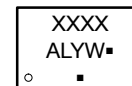
**DETAIL B**  
ALTERNATE  
CONSTRUCTIONS

**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20	REF
b	0.20	0.30
D	2.50	BSC
D2	0.85	1.15
E	3.50	BSC
E2	1.85	2.15
e	0.50	BSC
K	0.20	---
L	0.35	0.45
L1	---	0.15

**GENERIC MARKING  
DIAGRAM\***

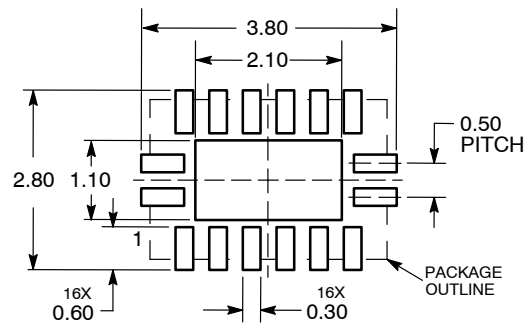


- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

**RECOMMENDED  
SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

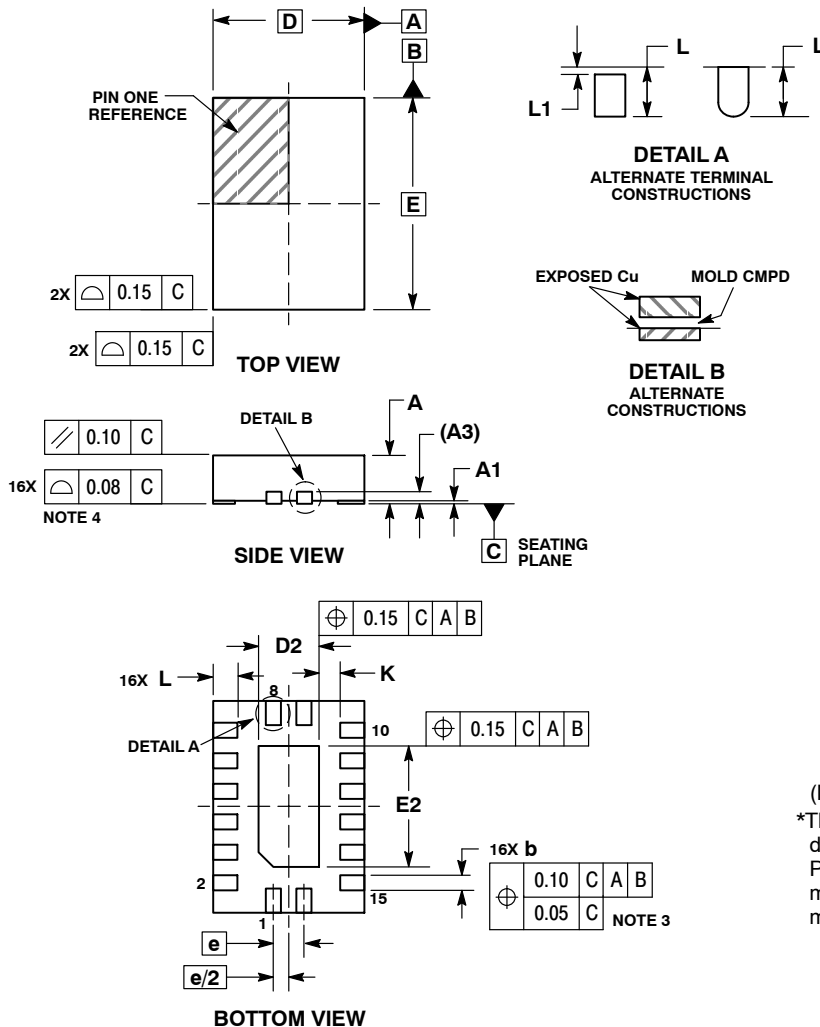
\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



SCALE 2:1

QFN16, 2.5x3.5, 0.5P  
CASE 485AW  
ISSUE O

DATE 11 DEC 2008

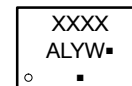


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20 REF	
b	0.20	0.30
D	2.50 BSC	
D2	0.85	1.15
E	3.50 BSC	
E2	1.85	2.15
e	0.50 BSC	
K	0.20	---
L	0.35	0.45
L1	---	0.15

GENERIC MARKING  
DIAGRAM\*

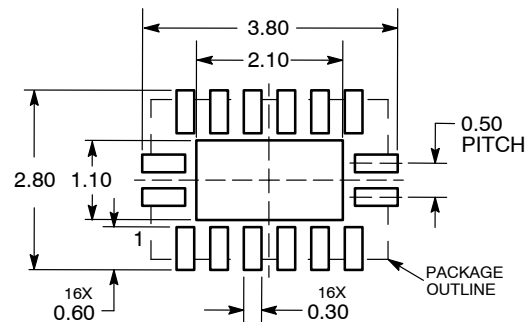


- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED  
SOLDERING FOOTPRINT\*

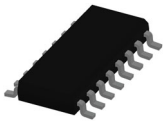


DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	QFN16, 2.5X3.5, 0.5P	PAGE 1 OF 1

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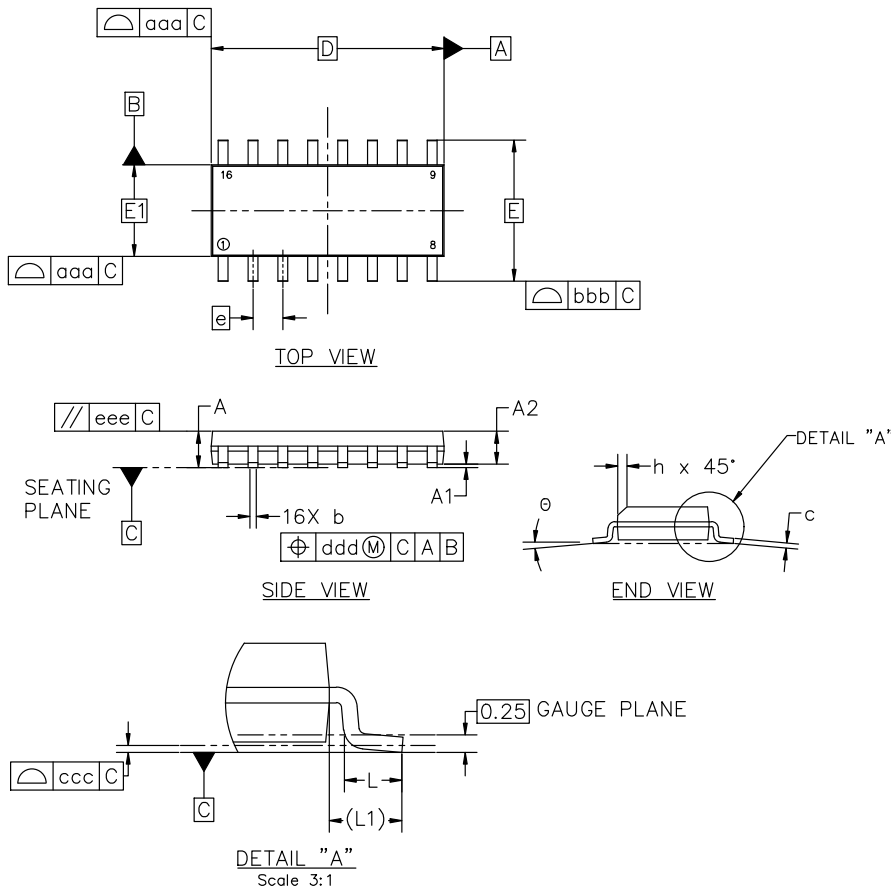


SOIC-16 9.90x3.90x1.50 1.27P  
CASE 751B  
ISSUE L

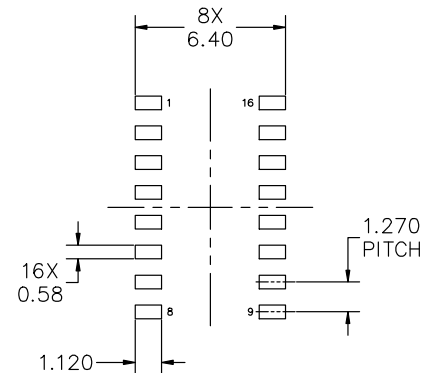
DATE 29 MAY 2024

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. DIMENSION IN MILLIMETERS. ANGLE IN DEGREES.
3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15mm PER SIDE.
5. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127mm TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION.



MILLIMETERS			
DIM	MIN	NOM	MAX
A	1.35	1.55	1.75
A1	0.00	0.05	0.10
A2	1.35	1.50	1.65
b	0.35	0.42	0.49
c	0.19	0.22	0.25
D	9.90 BSC		
E	6.00 BSC		
E1	3.90 BSC		
e	1.27 BSC		
h	0.25	---	0.50
L	0.40	0.83	1.25
L1	1.05 REF		
θ	0°	---	7°
TOLERANCE OF FORM AND POSITION			
aaa	0.10		
bbb	0.20		
ccc	0.10		
ddd	0.25		
eee	0.10		



RECOMMENDED MOUNTING FOOTPRINT

\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE onsemi SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D

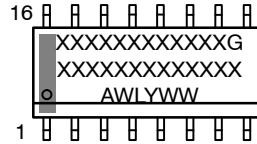
<b>DOCUMENT NUMBER:</b>	<b>98ASB42566B</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>SOIC-16 9.90X3.90X1.50 1.27P</b>	<b>PAGE 1 OF 2</b>

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SOIC-16 9.90x3.90x1.50 1.27P  
CASE 751B  
ISSUE L

DATE 29 MAY 2024

GENERIC  
MARKING DIAGRAM\*



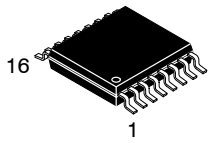
XXXXX = Specific Device Code  
A = Assembly Location  
WL = Wafer Lot  
Y = Year  
WW = Work Week  
G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

<p>STYLE 1:</p> <p>PIN 1. COLLECTOR</p> <p>2. BASE</p> <p>3. EMITTER</p> <p>4. NO CONNECTION</p> <p>5. EMITTER</p> <p>6. BASE</p> <p>7. COLLECTOR</p> <p>8. COLLECTOR</p> <p>9. BASE</p> <p>10. EMITTER</p> <p>11. NO CONNECTION</p> <p>12. EMITTER</p> <p>13. BASE</p> <p>14. COLLECTOR</p> <p>15. EMITTER</p> <p>16. COLLECTOR</p>	<p>STYLE 2:</p> <p>PIN 1. CATHODE</p> <p>2. ANODE</p> <p>3. NO CONNECTION</p> <p>4. CATHODE</p> <p>5. CATHODE</p> <p>6. NO CONNECTION</p> <p>7. ANODE</p> <p>8. CATHODE</p> <p>9. CATHODE</p> <p>10. ANODE</p> <p>11. NO CONNECTION</p> <p>12. CATHODE</p> <p>13. CATHODE</p> <p>14. NO CONNECTION</p> <p>15. ANODE</p> <p>16. CATHODE</p>	<p>STYLE 3:</p> <p>PIN 1. COLLECTOR, DYE #1</p> <p>2. BASE, #1</p> <p>3. EMITTER, #1</p> <p>4. COLLECTOR, #1</p> <p>5. COLLECTOR, #2</p> <p>6. BASE, #2</p> <p>7. EMITTER, #2</p> <p>8. COLLECTOR, #2</p> <p>9. COLLECTOR, #3</p> <p>10. BASE, #3</p> <p>11. EMITTER, #3</p> <p>12. COLLECTOR, #3</p> <p>13. COLLECTOR, #4</p> <p>14. BASE, #4</p> <p>15. EMITTER, #4</p> <p>16. COLLECTOR, #4</p>	<p>STYLE 4:</p> <p>PIN 1. COLLECTOR, DYE #1</p> <p>2. COLLECTOR, #1</p> <p>3. COLLECTOR, #2</p> <p>4. COLLECTOR, #2</p> <p>5. COLLECTOR, #3</p> <p>6. COLLECTOR, #3</p> <p>7. COLLECTOR, #4</p> <p>8. COLLECTOR, #4</p> <p>9. BASE, #4</p> <p>10. EMITTER, #4</p> <p>11. BASE, #3</p> <p>12. EMITTER, #3</p> <p>13. BASE, #2</p> <p>14. EMITTER, #2</p> <p>15. BASE, #1</p> <p>16. EMITTER, #1</p>
<p>STYLE 5:</p> <p>PIN 1. DRAIN, DYE #1</p> <p>2. DRAIN, #1</p> <p>3. DRAIN, #2</p> <p>4. DRAIN, #2</p> <p>5. DRAIN, #3</p> <p>6. DRAIN, #3</p> <p>7. DRAIN, #4</p> <p>8. DRAIN, #4</p> <p>9. GATE, #4</p> <p>10. SOURCE, #4</p> <p>11. GATE, #3</p> <p>12. SOURCE, #3</p> <p>13. GATE, #2</p> <p>14. SOURCE, #2</p> <p>15. GATE, #1</p> <p>16. SOURCE, #1</p>	<p>STYLE 6:</p> <p>PIN 1. CATHODE</p> <p>2. CATHODE</p> <p>3. CATHODE</p> <p>4. CATHODE</p> <p>5. CATHODE</p> <p>6. CATHODE</p> <p>7. CATHODE</p> <p>8. CATHODE</p> <p>9. ANODE</p> <p>10. ANODE</p> <p>11. ANODE</p> <p>12. ANODE</p> <p>13. ANODE</p> <p>14. ANODE</p> <p>15. ANODE</p> <p>16. ANODE</p>	<p>STYLE 7:</p> <p>PIN 1. SOURCE N-CH</p> <p>2. COMMON DRAIN (OUTPUT)</p> <p>3. COMMON DRAIN (OUTPUT)</p> <p>4. GATE P-CH</p> <p>5. COMMON DRAIN (OUTPUT)</p> <p>6. COMMON DRAIN (OUTPUT)</p> <p>7. COMMON DRAIN (OUTPUT)</p> <p>8. SOURCE P-CH</p> <p>9. SOURCE P-CH</p> <p>10. COMMON DRAIN (OUTPUT)</p> <p>11. COMMON DRAIN (OUTPUT)</p> <p>12. COMMON DRAIN (OUTPUT)</p> <p>13. GATE N-CH</p> <p>14. COMMON DRAIN (OUTPUT)</p> <p>15. COMMON DRAIN (OUTPUT)</p> <p>16. SOURCE N-CH</p>	

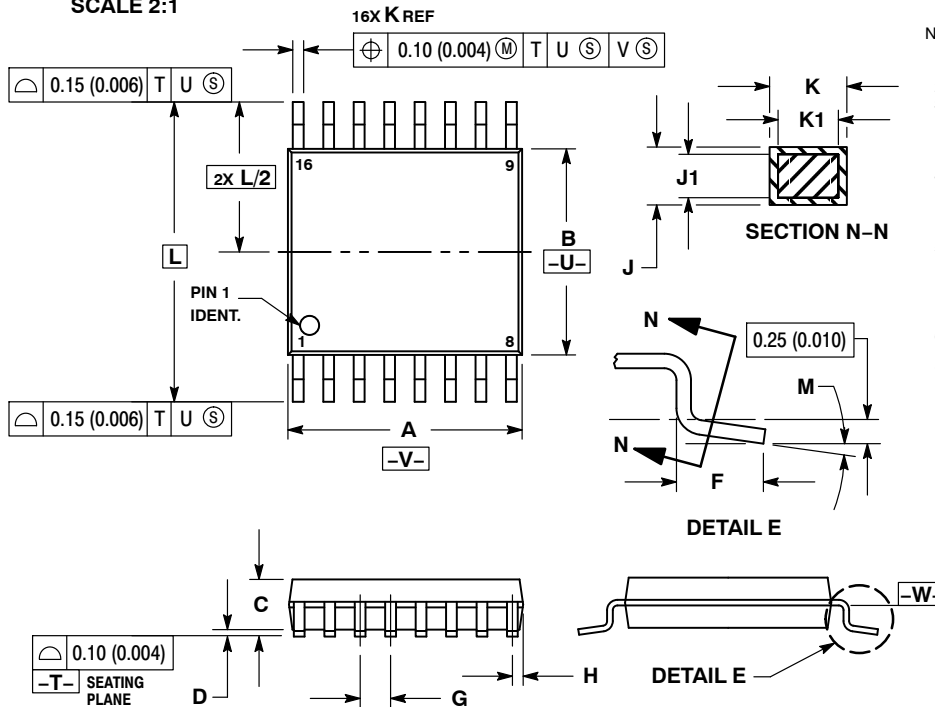
<b>DOCUMENT NUMBER:</b>	<b>98ASB42566B</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>SOIC-16 9.90X3.90X1.50 1.27P</b>	<b>PAGE 2 OF 2</b>

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TSSOP-16 WB  
CASE 948F  
ISSUE B

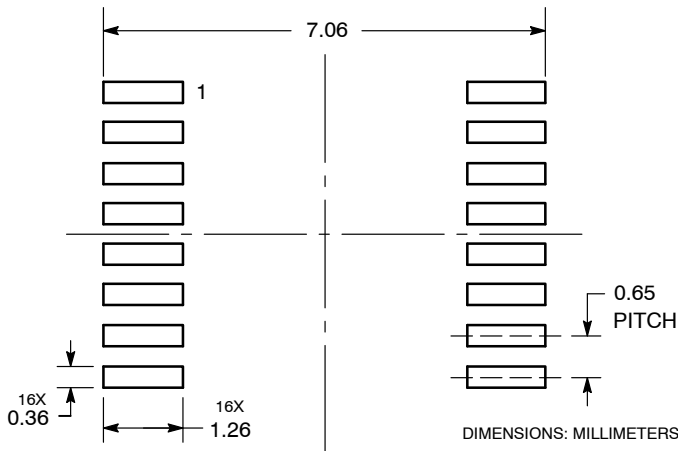
DATE 19 OCT 2006



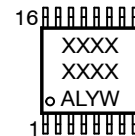
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
  6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

RECOMMENDED  
SOLDERING FOOTPRINT\*



GENERIC  
MARKING DIAGRAM\*



- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- G or ■ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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